

9. (Amended) A mounting structure for mounting a semiconductor device, that is connected to a substrate via a composite connection material formed of a core, a conductor covering said core, and a single-layer connection material, wherein  
said composite connection material and said single-layer connection material have a substrate contact portion contacting said substrate and an electrode contact portion contacting an electrode of said semiconductor device, respectively, and melting points of said substrate contact portion are both lower than those of said electrode contact portions.

*AS* Marked-up versions of the amended passages from the specification and claims are provided in an annex to this amendment.

**REMARKS**

Claims 1 through 9 are pending in the subject application. Claims 1-9 stand rejected under 35 U.S.C. 102(b). Claims 1, 6, and 9 have been amended. No new matter has been added to the application.

The Applicants appreciate the Examiner's thorough examination of the subject application and respectfully request reconsideration of the subject application based on the above amendments and the following remarks.

**FORMALITIES**

The Examiner has acknowledged Applicants' claim of foreign priority; however, asserts that a certified copy of the Japanese application has not been filed. However, a certified copy of the Japanese application was filed along with the application as